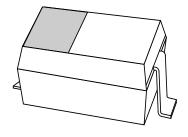
DISCRETE SEMICONDUCTORS

DATA SHEET



BB135UHF variable capacitance diode

Product specification Supersedes data of 1998 Sep 15 2004 Mar 01



UHF variable capacitance diode

BB135

FEATURES

- · Excellent linearity
- Very small plastic SMD package.
- C28: 1.9 pF; ratio: 10
- Low series resistance.

APPLICATIONS

- Electronic tuning in UHF television tuners.
- Radio upconversion concepts
- VCO.

DESCRIPTION

The BB135 is a variable capacitance diode, fabricated in planar technology, and encapsulated in the SOD323 very small plastic SMD package.

The matched type, BB134 has the same specification.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode

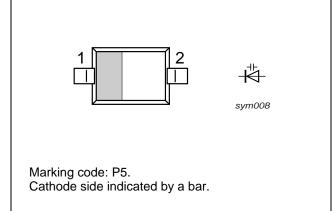


Fig.1 Simplified outline (SOD323; SC-76) and symbol.

ORDERING INFORMATION

TYPE	PACKAGE				
NUMBER	NAME	ME DESCRIPTION VERSIO			
BB135	_	plastic surface mounted package; 2 leads SC			

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V _R	continuous reverse voltage	_	30	V
I _F	continuous forward current	_	20	mA
T _{stg}	storage temperature	-55	+150	°C
Tj	operating junction temperature	-55	+125	°C

UHF variable capacitance diode

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ELECTRICAL CHARACTERISTICS

 $T_j = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _R	reverse current	V _R = 30 V; see Fig.3	_	10	nA
		V _R = 30 V; T _j = 85 °C; see Fig.3	_	200	nA
r _s	diode series resistance	f = 470 MHz; note 1	_	0.75	Ω
C _d	diode capacitance	V _R = 0.5 V; f = 1 MHz; see Figs 2 and 4	17.5	21	pF
		V _R = 28 V; f = 1 MHz; see Figs 2 and 4	1.7	2.1	pF
$\frac{C_{d(0.5V)}}{C_{d(28V)}}$	capacitance ratio	f = 1 MHz	8.9	12	

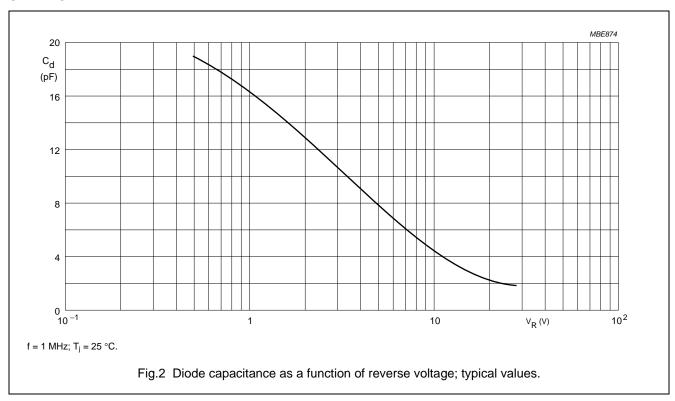
Note

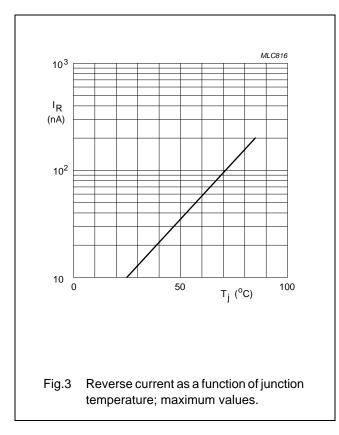
1. V_R is the value at which $C_d = 9$ pF.

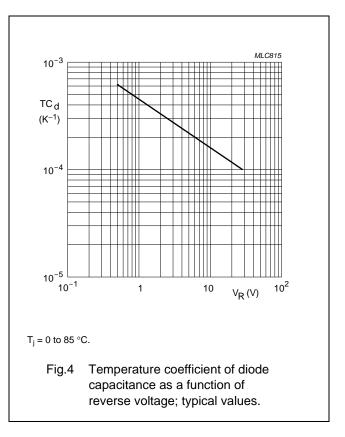
UHF variable capacitance diode

BB135

GRAPHICAL DATA





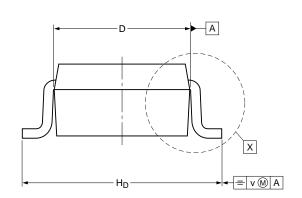


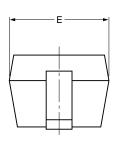
UHF variable capacitance diode

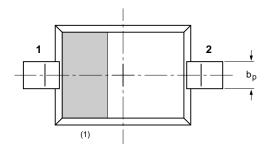
BB135

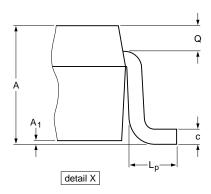
PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads SOD323











DIMENSIONS (mm are the original dimensions)

UNIT	Α	A ₁ max	bp	С	D	E	H _D	Lp	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15		0.2

Note

1. The marking bar indicates the cathode

OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA		PROJECTION	
SOD323			SC-76			-03-12-17- 06-03-16

UHF variable capacitance diode

BB135

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

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UHF variable capacitance diode

BB135

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2004 Mar 01

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provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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Printed in The Netherlands R77/04/pp8 Date of release: 2004 Mar 01